

EPIC-QM57

Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> Pass <input type="checkbox"/> Fail <input type="checkbox"/> Pass with Deviation Comment: _____			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	0
Defect Unsolved	0	0	0	0

Issue date

2010/04/27

Approval

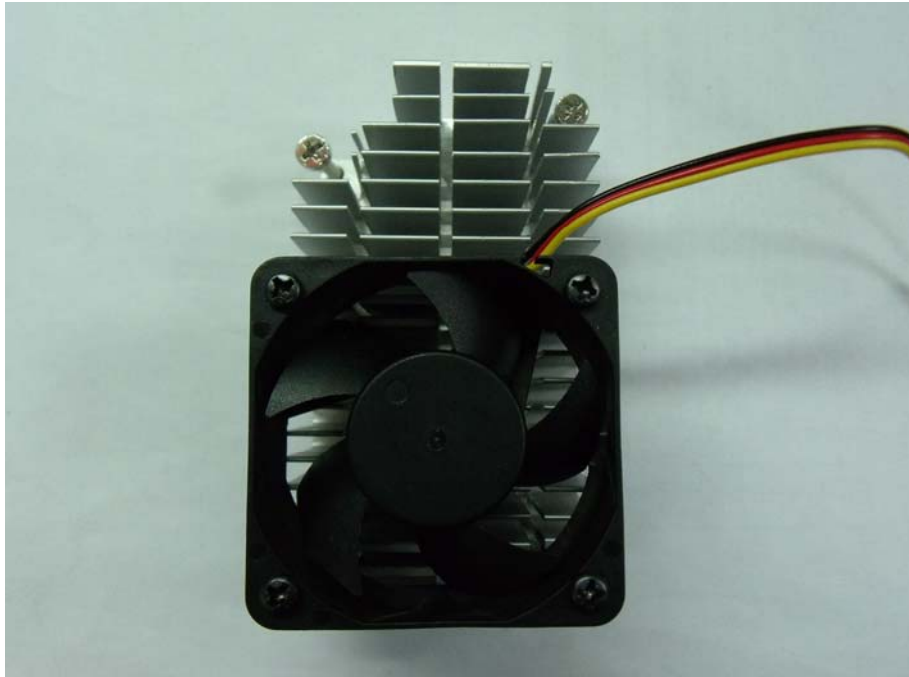
Jansin Lee

Test Engineer

Anderson Lin

Sample Configuration & Quantity Under Test

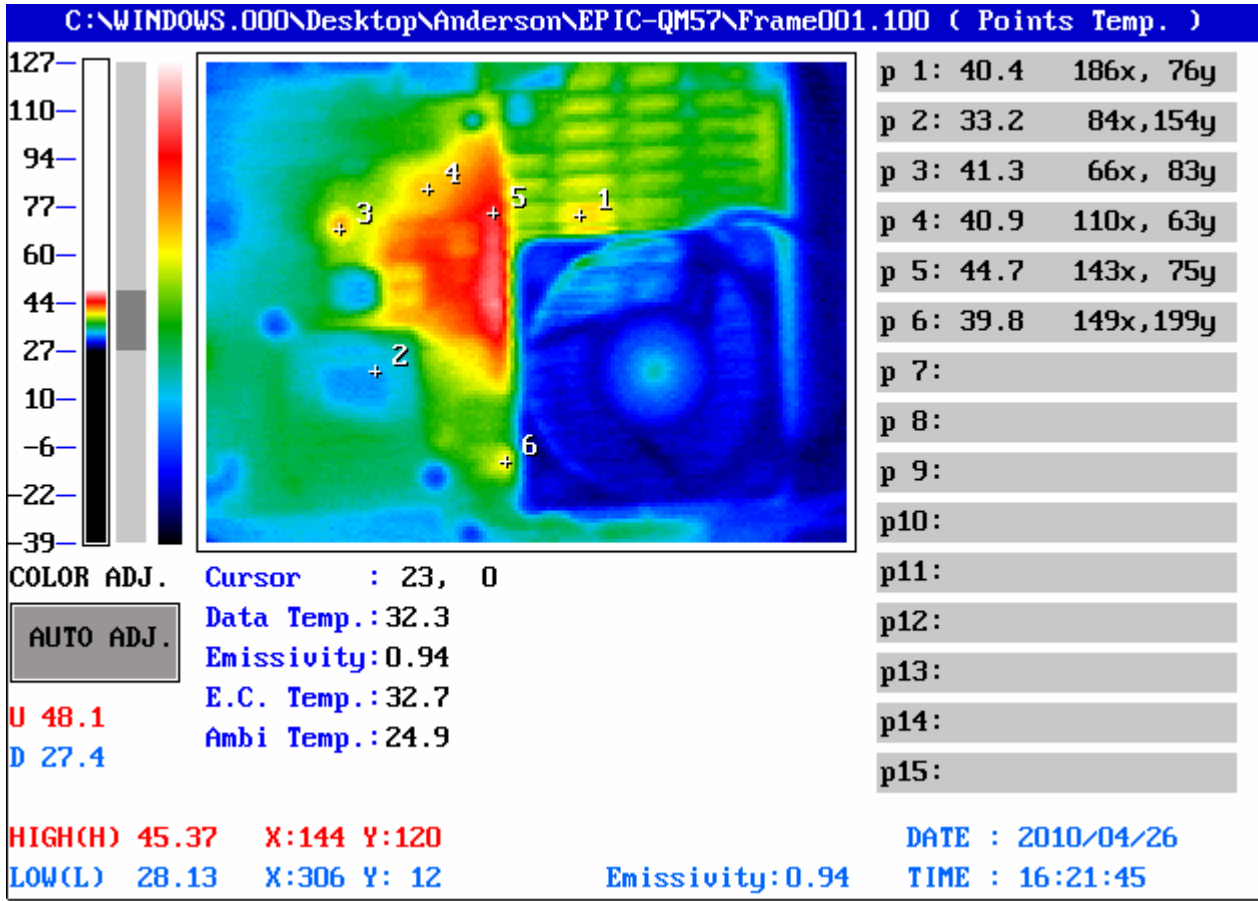
- CPU Board: EPIC-QM57 Rev.A0.2
- Carrier Board:N/A
- CPU: Intel ® Core™ i7-620M Processor (4M Cache, 2.66 GHz)
- Memory: SAMSUNG 2GB SODIMM DDR3-1066 (SEC 816 HCF8 K4B1G0846D)
- HDD: FUJITSU 2.5 SATA H.D MHY2080BH 80GB
- BIOS : EPIC-QM57 BIOS Rev 4.6.3.7 (04/01/2010)
- Test Software: Windows XP sp3 / Run Prime95 v25.9
- AT Power Supply: EMACS SP2-4400F
- Cooler:

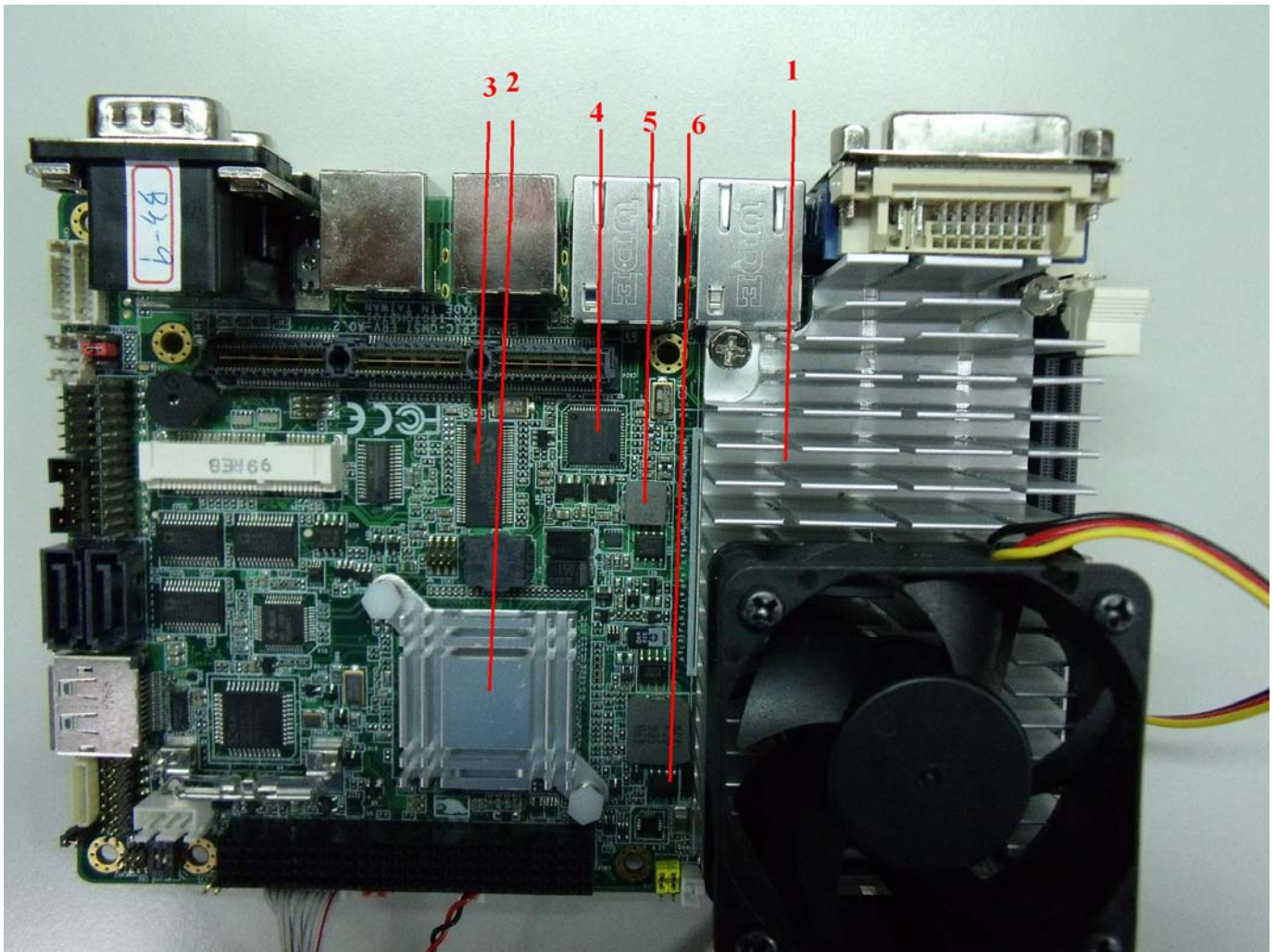


Thermal Image Analysis

1. Test Date: 04/27/2010
2. Test Product: EPIC-QM57
3. Test Site: AAEON QA Internal Lab.
4. Temperature Measurement:
 1. IR Scanner: Infrared Camera
NIPPON AVIONICS CO., LTD.
Model: TVS-100
Date of Calibration: 09/17/09
Serial Number: 0179L2746
5. Test Condition:
 - Component Side-1: 24.9°C
 - Component Side-2: 25.1°C
 - Component Side-3: 24.1°C
6. Test Software:
Windows XP sp3 / Run Prime 95 v25.9
7. Take Picture Time:
After power on 2 hours

Temperature Profile Test:
Component Side-1:





Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				24.9°C	60°C	
1	U23	(TF)ZIF mPGA989M SKT.989P.for Arrandale.FOXCONN.DWG-PZ98927-3641-01F	105	40.4	75.5	
2	U11	(TF)IC.SMD.Chipset PCH.INTEL.BD82QM57 SLGZQ	120	33.2	68.3	
3	U30	(TF)IC.SMD.TSSOP 64P.CLOCK GENERATOR.SILEGO.SLG505YC264BTTR	100	41.3	76.4	
4	U33	(TF)IC.SMD.QFN 64P.PCI-E GigaBit Ethernet Chipset.Intel.WG82574L SLBA8	109	40.9	76	
5	L7	(TF)COIL.4.7uH.+/-20%.SMD.7.3*6.8*3.0mm.DCR=37mohm.Irms=5.5Amp.GOTREND.GSTC063P-4R7MN	155	44.7	79.8	
6	Q11	(TF)PWR.SMD.SOT-323.N-Channel.Mosfet.Vgs=±20V,Ids=340mA.Rds=1.6/2.5ohm.ON.2N7002WT1G	125	39.8	74.9	

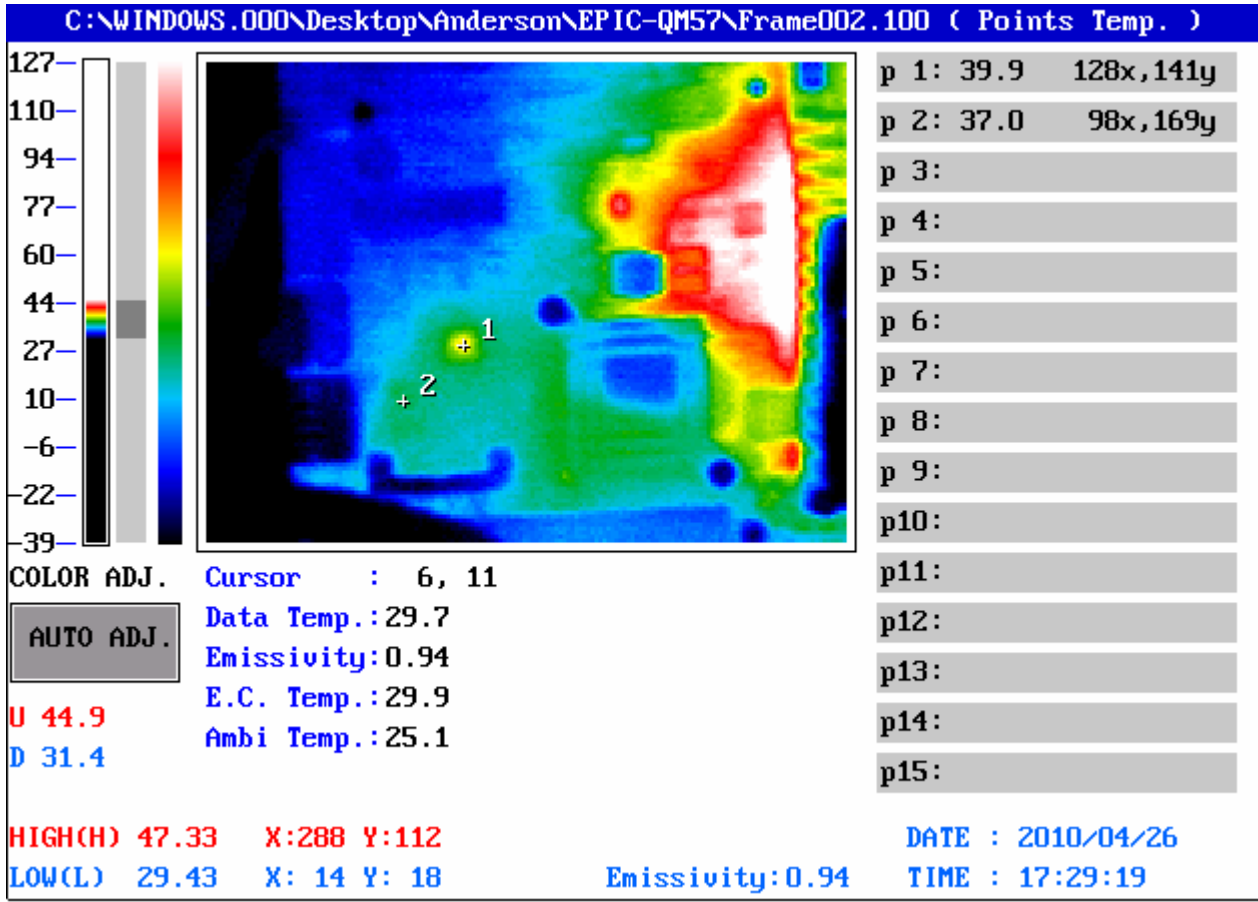
Note(*):

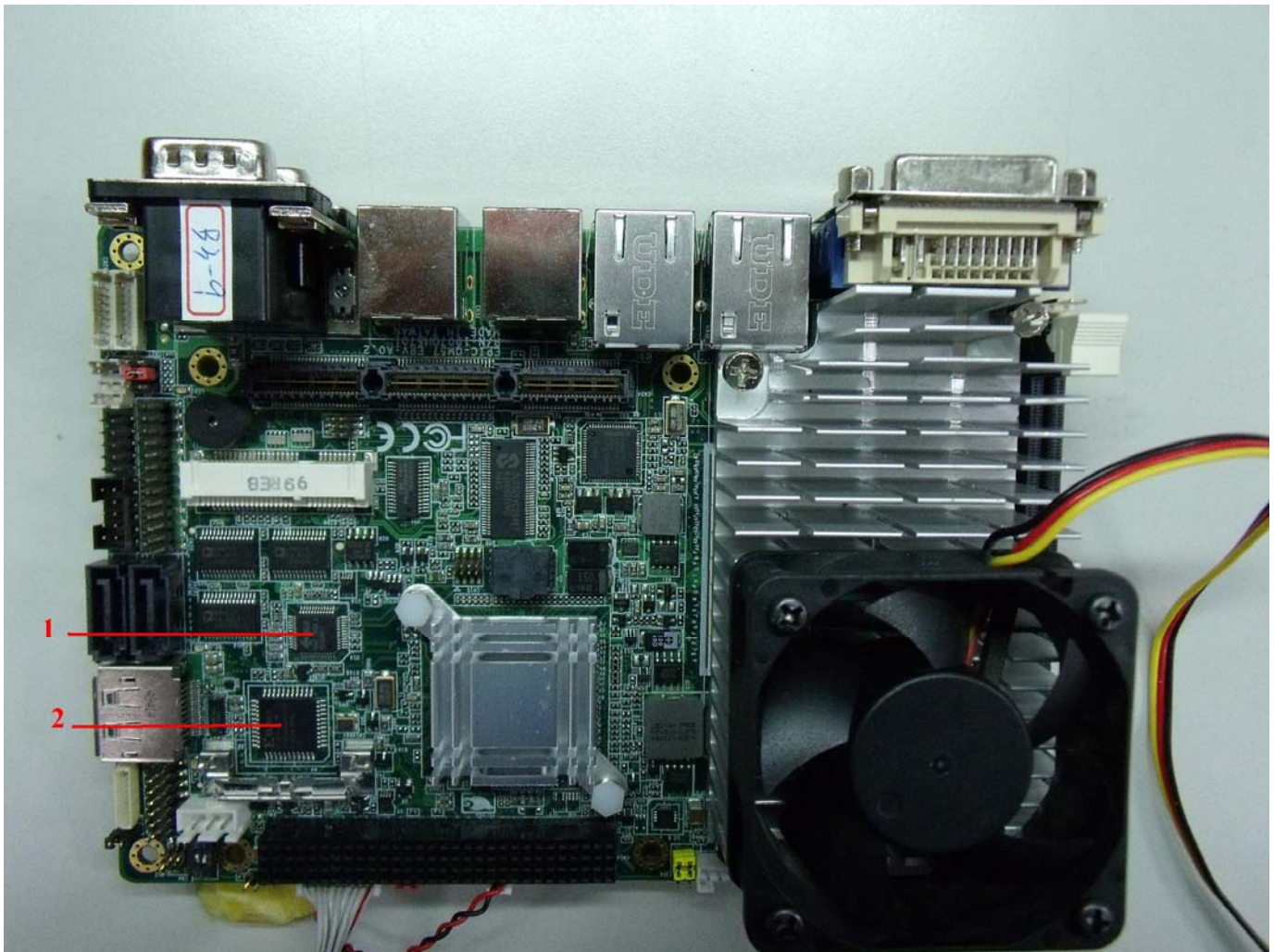
1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
- **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.

Component Side-2:





Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.1°C	60°C	
1	U14	(TF)IC.SMD.LQFP 48P.PCI Express to.PATA Host Controller.JMicron.JMB368-LGGZ0A	100	39.9	74.8	
2	U10	(TF)IC.SMD.VQ 44P.CoolRunner-II CPLD.Xilinx.XC2C64A-7VQG44C	125	37.0	71.9	

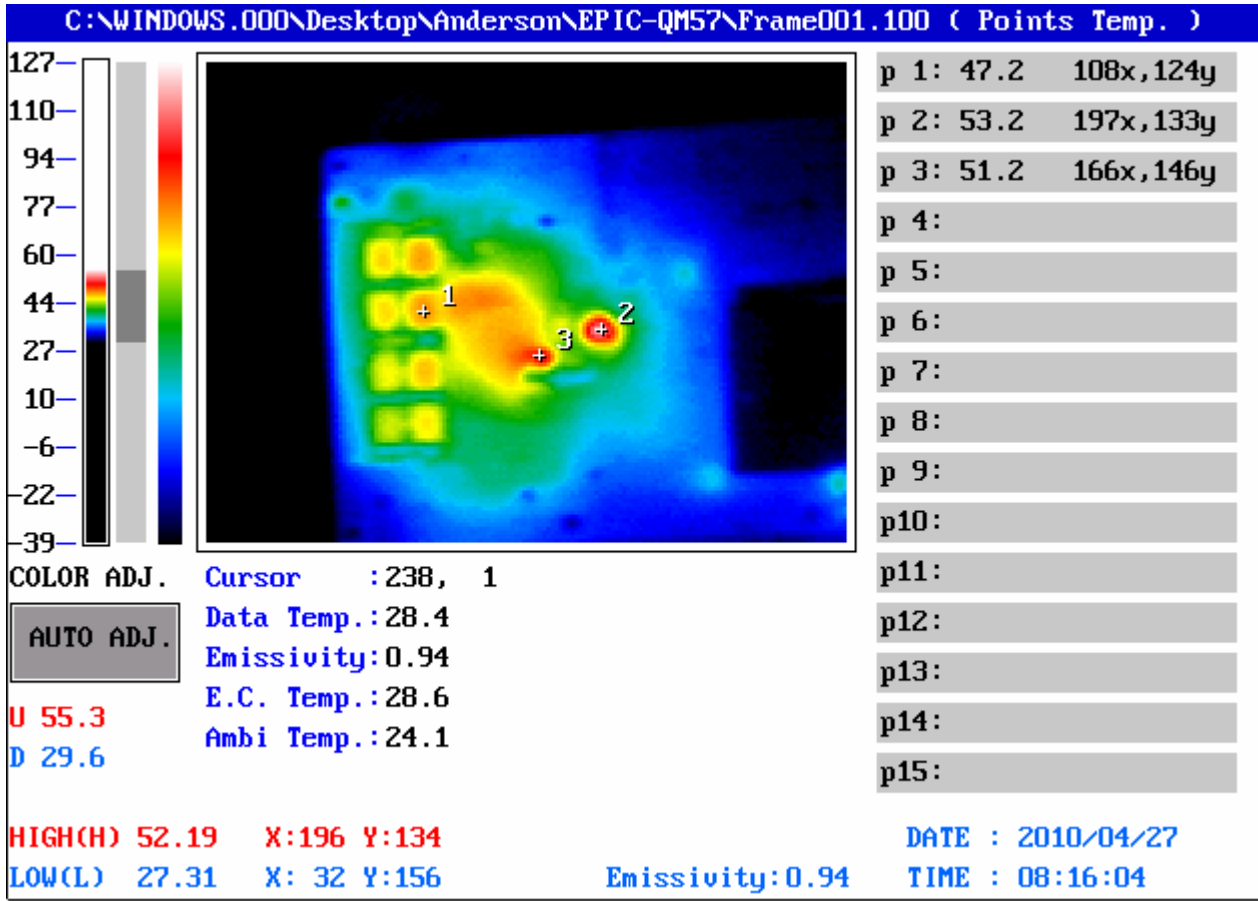
Note(*):

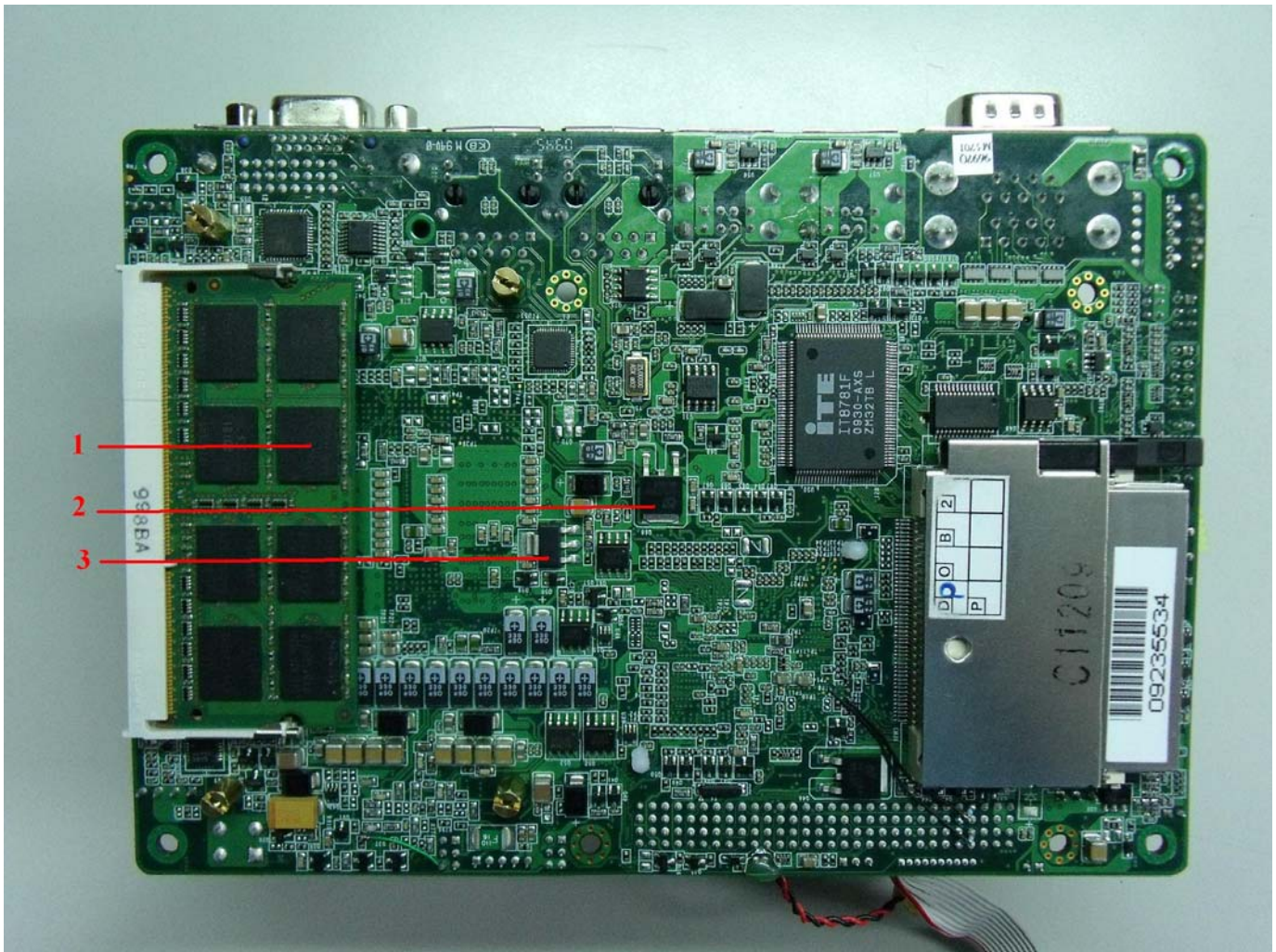
- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- **Fail** : Tm > Tc+5°C; The measured value is over specification plus margin.
- **Margin** : Tc+5°C > Tm > Tc-10°C; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** : Tm < Tc-10°C; The measured value is with safety margin.

Component Side-3:





Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				24.1°C	60°C	
1	CN37	Memory		47.2	83.1	
2	Q68	(TF)REG.SMD.TO-252.5A linear Regulator.ANPEC.APL1084-UC-TRL	125	53.2	89.1	
3	Q62	(TF)REG.SMD SOT223.1A Adjustable Linear Regulator.ANPEC.APL1117-VC-TRL	125	51.2	87.1	

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.
3. **Judgment Criteria:**
 - **Fail** : Tm > Tc+5°C; The measured value is over specification plus margin.
 - **Margin** : Tc+5°C > Tm > Tc-10°C; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : Tm < Tc-10°C; The measured value is with safety margin.